



PYRALUX® FLEXIBLE CIRCUIT MATERIALS

In the sky, in your car, in your pocket...

At DuPont, we're not just suppliers; we're total solution providers and your partners in innovation. As a long-established provider of laminate materials, we bring deep expertise and applications development to your project. With our Pyralux® laminate portfolio, we're committed to tackling today's needs and anticipating tomorrow's challenges. We collaborate with you to solve your toughest problems, bringing forward ideas and executing them with precision. Our hands-on approach ensures that we work side-by-side with you, pushing the boundaries of what's possible in materials, design, and processes to drive our shared success.

2024

Pyralux® ML

- Newest addition to the Pyralux® laminate portfolio
- Polyimide product clad using metal alloys, possibly in combination with copper foils
- Affords thermal resistance, conductivity, and resistivity essential for thermal management of high-reliability, temperature-sensitive devices, e.g., heaters, thermocouples, sensors, flex printed circuits
- *Key markets:* Aerospace, defense, automotive/EV, AI, networking

2020

Pyralux® HP

- Specifically designed for OEMs and PCB design manufacturers
- Epoxy-based adhesive system creates an optimized low-loss, high-reliability solution suitable for multi-layer flex and rigid-flex PCBs
- *Key markets:* Communications, defense, automotive, medical

2015

Pyralux® HT

- Thermoplastic polyimide bonding film that can be used as coverlay, bondply or sheet adhesive
- Designed for extreme high-temperature applications; can withstand harsh environments
- *Key markets:* Aerospace, defense, medical, oil and gas exploration

2010

Pyralux® TK

- Double-sided copper-clad laminate with a proprietary layered dielectric made with Kapton® polyimide and fluoropolymer films
- Designed for high-speed digital and high-frequency flexible circuits
- *Key markets:* Datacom and telecom, high-speed networking servers, high-end computing, storage servers, signal processing

1999

Pyralux® AC

- Single-sided adhesiveless copper-clad laminate
- Designed for circuits that require thin, lightweight, and high-density circuitry, along with chip-on-flex attachment
- *Key markets:* Mobile devices, automotive, display drivers, multilayer digital cameras, rigid-flex camcorder circuits

1994

Pyralux® AP

- All-polyimide laminate advancing rigid-flex technology
- Offers excellent thermal, mechanical, and electrical properties for high-performance high-reliability environments
- *Key markets:* Aerospace, defense, space projects such as Mars Exploration Rovers, the James Webb Space Telescope, and satellites; mobile devices, computers, military electronics, automotive, medical equipment

1993

Pyralux® FR

- Flexible composite family of coverlay, bondply unsupported acrylic sheet adhesive and copper-clad laminate
- UL flame-retardant recognition
- *Key markets:* Consumer electronics, computer networking, commercial aircraft, medical devices, mobile devices

1979

Pyralux® LF

- Flexible composite family of coverlay, bondply unsupported acrylic sheet adhesive and copper-clad laminate
- High bond strength and resistance, ideally suited for mass production, where uniformity, quality and reliability are paramount
- *Key markets:* Aerospace and defense, mobile devices, computers, military electronics, automotive, medical equipment

